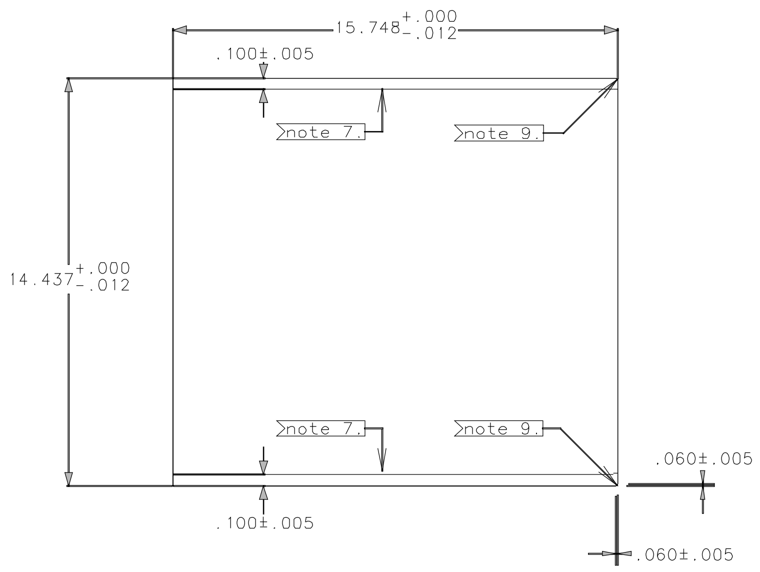
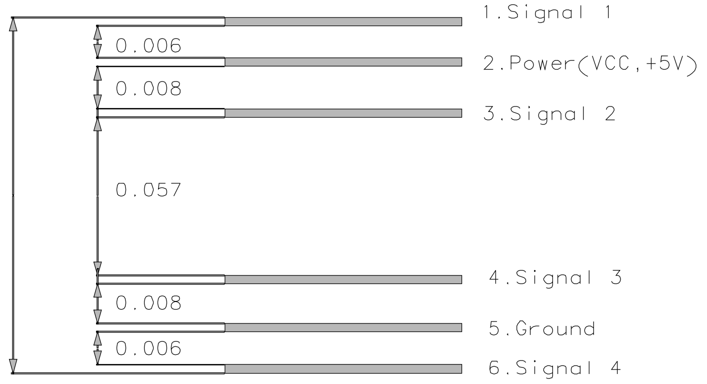
DWG. NO. B - 2393 SH 1 REV B





BOARD's DRILL SCHEDULE (inches)

SYMBOL	FHS	COUNT	PLATED	TOLERANCE	COMMENT
○	.018	212	YES	---	
⊞	.02	2187	YES	---	
⦶	.0236	378	YES	---	Note 12.
⊟	.028	503	YES	---	
⊖	.035	80	YES	---	
◫	.041	440	YES	---	
⊕	.052	2	YES	---	
□	.057	11	YES	---	
	.05905	1	NO	---	
	.106	15	NO	---	
	.113	6	NO	---	

Board Characteristics :

0. All dimensions are given in inches unless specified otherwise.
1. Material: FR4 - Tg > 170C.
2. Minimum Trace Width 0.007" on all layers.
3. Minimum Clearence 0.006" on all layers.
4. 1 oz copper for all Trace and Power Layers.
5. Apply ENTEC or equivalent Organic Coating over bare copper. Apply Solder Mask over bare copper.
6. Board Thickness: 0.093 +/- 0.008".
7. Mill the Top and Bottom 0.1" of board. on the solder side to a thickness of 0.062" +/-0.008".
8. Silkscreen on Component and Solder Sides.
9. 45 degree chamfer.
10. Hole diameter tolerances : +/- 0.002" unless specified otherwise.
11. Interlayer spacing : as specified.
12. This is a pressfit technology through hole with the following specs:
    12-1. Finished hole size: 0.6mm +/- 0.05mm;
    12-2. Drilled hole size: 0.7mm +/- 0.02mm;
    12-3. Thickness of through hole plating: min 25 μm Cu;
    12-4. Inside through hole: OSP with 0.12 - 0.15 μm.

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES TOLERANCES ARE: FRACTIONS DECIMALS ANGLES .XX .XXX DO NOT SCALE DRAWING	CONTRACT NO.	ENRICO FERMI INST., UNIV. OF CHICAGO ELECTRONICS DEVELOPEMENT GROUP
TREATMENT	APPROVALS / DATE	TITLE CDF L1 PreFRED Board Specification Drawing
FINISH	DRAWN M. Bogdan 6/23/99	SIZE B / FSCM NO. / DWG. NO. B - 2393 / REV. B
SIMILAR TO / ACT. WT / CALC WT	CHECKED H. Sanders 6/23/99	SCALE / SHEET 1 of 1
	ISSUED	

THIS SHEET IS COMPUTER GENERATED